

Form PTO-1449

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

OCT 29 2003

(Use a separate sheet if necessary)

Docket Number (Sequence)

TSMC-01-1388

Application Number

10/628,914

Applicant

Chih-Ming Ke et al.

Filing Date

07/29/03

Priority Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
we	611468	19/5/00	Komatsu	250	201.3	6/4/98
we	591671	6/29/99	Butsch et al.	430	30	3/13/97
we	6130432	10/10/00	Pfeiffer et al.	250	396ML	4/13/99
we	5025165	6/18/91	Chen et al.	250	491.1	3/26/90
we	6066849	5/23/00	Masnaghetti et al.	250	310	9/8/98

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)

we	-	"193nm resist shrinkage", by Su et al., Solid State Technology, May 2001, pp. 52-54 and 57.
we	-	U.S. Patent Application Serial No. 10/047,266, Filed 1/14/02, "Reducing Photoresist Shrinkage via Plasma Treatment"
we	-	assigned to the same assignee.

EXAMINER

ZIA R. HASHMI

DATE CONSIDERED

6/29/04

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.